RELIABILITY REPORT

FOR

MAX1742EEE+

PLASTIC ENCAPSULATED DEVICES

June 17, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX1742EEE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX1742/MAX1842 constant-off-time, pulse-width- modulated (PWM) step-down DC-DC converters are ideal for use in 5V and 3.3V to low-voltage conversion necessary in notebook and subnotebook computers. These devices feature internal synchronous rectification for high efficiency and reduced component count. They require no external Schottky diode. The internal 90m PMOS power switch and 70m NMOS synchronous-rectifier switch easily deliver continuous load currents up to 1A. The MAX1742/MAX1842 produce a preset 2.5V, 1.8V, or 1.5V output voltage or an adjustable output from 1.1V to VIN. They achieve efficiencies as high as 95%. The MAX1742/MAX1842 use a unique current-mode, constant-off-time, PWM control scheme, which includes Idle Mode™ to maintain high efficiency during light-load operation. The programmable constant-off-time architecture sets switching frequencies up to 1MHz, allowing the user to optimize performance trade-offs between efficiency, output switching noise, component size, and cost. Both devices are designed for continuous output currents up to 1A. The MAX1742 uses a peak current limit of 1.3A (min) and is suitable for applications requiring small external component size and high efficiency. The MAX1842 has a higher current limit of 3.1A (min) and is intended for applications requiring an occasional burst of output current up to 2.7A. Both devices also feature an adjustable soft-start to limit surge currents during startup, a 100% duty cycle mode for low-dropout operation, and a low-power shutdown mode that disconnects the input from the output and reduces supply current below 1µA. The MAX1742/MAX1842 are available in 16-pin QSOP packages. For similar devices that provide continuous output currents up to 2A and 3A, refer to the MAX1644 and MAX1623 data sheets.

II. Manufacturing Information

A. Description/Function:	1A/2.7A, 1MHz, Step-Down Regulators with Synchronous Rectification and Internal Switches
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	July 22, 2000

III. Packaging Information

A. Package Type:	16-pin QSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0599
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	37°C/W
L. Multi Layer Theta Ja:	103.7°C/W
M. Multi Layer Theta Jc:	37°C/W

IV. Die Information

A. Dimensions:	86 X 108 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Al/0.5% Cu
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 448 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 2.4 \times 10^{-9}$

$\lambda = 2.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the B8 Process results in a FIT Rate of 1.86 @ 25C and 22.5 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The PX56 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX1742EEE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	448	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data